L Number	Hits	Search Text	DB	Time stamp
9	8	("4082394" | "4322778" | "5355283" | "5537051" | "5652185" | "5777381" | "5977617" | "5994773").PN.	USPAT	2002/05/31 07:59
10	2	(("4082394" | "4322778" | "5355283" | "5537051" | "5652185" | "5777381" | "5977617" | "5994773").PN.) and thermal	USPAT	2002/05/31 07:59
-	5939	semiconductor adj chip and resin	USPAT; US-PGPUB	2002/05/29 17:48
-	1754	(semiconductor adj chip and resin) and encapsulat$3	USPAT; US-PGPUB	2002/05/29 17:48
-	147	((semiconductor adj chip and resin) and encapsulat$3) and adhesive adj tape	USPAT; US-PGPUB	2002/05/30 18:53
-	60	((semiconductor adj chip and resin) and encapsulat$3) and pressure adj2 adhesive	USPAT; US-PGPUB	2002/05/29 17:58
-	34	("3908075" | "4410905" | "4539472" | "4595945" | "4598308" | "4616413" | "4754319" | "4796078" | "4862245" | "4937203" | "4965654" | "4996587" | "5070390" | "5075252" | "5099309" | "5140404" | "5162264" | "5170328" | "5177032" | "5218229" | "5220195" | "5227232" | "5227338" | "5227662" | "5237201" | "5250839" | "5306670" | "5349234" | "5350947" | "5382830" | "5399903" | "5412247" | "5428247" | "5481436").PN.	USPAT	2002/05/29 17:54
-	8	5696032.URPN.	USPAT	2002/05/29 17:56
-	123	(((semiconductor adj chip and resin) and encapsulat$3) and adhesive adj tape) not (((semiconductor adj chip and resin) and encapsulat$3) and pressure adj2 adhesive)	USPAT; US-PGPUB	2002/05/29 17:59
-	1211	((semiconductor adj chip and resin) and encapsulat$3) and (adhesive or tape)	USPAT; US-PGPUB	2002/05/29 18:00
-	552	(((semiconductor adj chip and resin) and encapsulat$3) and (adhesive or tape)) and lead adj frame	USPAT; US-PGPUB	2002/05/29 17:59
-	362	((((semiconductor adj chip and resin) and encapsulat$3) and (adhesive or tape)) and lead adj frame) and (tape)	USPAT; US-PGPUB	2002/05/29 18:03
-	76	((((semiconductor adj chip and resin) and encapsulat$3) and adhesive adj tape) not (((semiconductor adj chip and resin) and encapsulat$3) and pressure adj2 adhesive)) and lead adj frame	USPAT; US-PGPUB	2002/05/29 18:01
-	241	((((semiconductor adj chip and resin) and encapsulat$3) and (adhesive or tape)) and lead adj frame) and (tape) with lead	USPAT; US-PGPUB	2002/05/29 18:03
-	40866	pressure adj sensitive	USPAT; US-PGPUB	2002/05/29 18:04
-	1183	(pressure adj sensitive) and thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:04
-	120	(pressure adj sensitive) same thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:11
-	9	("3725115" | "4379201" | "4574879" | "4714655" | "4869879" | "4908296" | "5213868" | "5366573" | "5462977").PN.	USPAT	2002/05/29 18:11
-	0	(("3725115" | "4379201" | "4574879" | "4714655" | "4869879" | "4908296" | "5213868" | "5366573" | "5462977").PN.) same thermal adj (shrinkage or expansion)	USPAT; US-PGPUB	2002/05/29 18:19
-	0	(("3725115" | "4379201" | "4574879" | "4714655" | "4869879" | "4908296" | "5213868" | "5366573" | "5462977").PN.) same thermal adj (contraction)	USPAT; US-PGPUB	2002/05/29 18:19
-	0	(pressure adj sensitive) same thermal adj (contraction)	USPAT; US-PGPUB	2002/05/29 18:19
-	25536	semiconductor adj chip	USPAT; US-PGPUB	2002/05/30 19:19

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-	3186	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage)	USPAT; US-PGPUB	2002/05/30 19:19
-	292	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or adhesive)	USPAT; US-PGPUB	2002/05/30 19:06
-	383	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)	USPAT; US-PGPUB	2002/05/30 19:11
-	220	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)	USPAT; US-PGPUB	2002/05/30 19:08
-	220	((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)	USPAT; US-PGPUB	2002/05/30 19:14
-	40	(((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)) and "%"	USPAT; US-PGPUB	2002/05/30 19:17
-	4	(((semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film)) and thermal adj (expansion or contraction or shrinkage) near5 (tape or film)) and "%" with thermal	USPAT; US-PGPUB	2002/05/30 19:17
-	42359	semiconductor adj chip	EPO; JPO; DERWENT	2002/05/30 19:19
-	1109	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage)	EPO; JPO; DERWENT	2002/05/30 19:19
-	167	(semiconductor adj chip) and thermal adj (expansion or contraction or shrinkage) with (tape or film or adhesive)	EPO; JPO; DERWENT	2002/05/30 19:29
-	1	("6284566").PN.	USPAT; US-PGPUB	2002/05/30 19:29
-	8	("4082394" | "4322778" | "5355283" | "5537051" | "5652185" | "5777381" | "5977617" | "5994773").PN.	USPAT	2002/05/31 07:59